

Abstract

Provided is a pressure-sensitive adhesive that has a sufficient adhesive strength and is reduced in high-temperature strain. Also provided is a pressure-sensitive adhesive tape including such pressure-sensitive adhesive. Also provided is a film substrate including such pressure-sensitive adhesive. Also provided is a pressure-sensitive adhesive film that has a sufficient adhesive strength and is reduced in high-temperature strain. Also provided is a pressure-sensitive adhesive tape including such pressure-sensitive adhesive film. Also provided is a film substrate including such pressure-sensitive adhesive film. The pressure-sensitive adhesive of the present invention has an adhesive strength to a surface of a polyimide film of 1 N or more, and a storage modulus of elasticity G' at 160°C of 1×10^5 Pa or more. The pressure-sensitive adhesive film of the present invention has an adhesive strength to a surface of a polyimide film of 1 N or more, a storage modulus of elasticity G' at 160°C of 1×10^4 Pa or more, and a thickness of 20 μm or less.